# **TOSHIBA**

### **Discrete Semiconductors**

2SK2078

### **Field Effect Transistor**

### Silicon N Channel MOS Type (r-MOS II.5)

### High Speed, High Current Switching Applications

#### **Features**

- Low Drain-Source ON Resistance
- R<sub>DS(ON)</sub> = 1.0Ω (Typ.) High Forward Transfer Admittance
- $|Y_{fs}| = 4.0S (Typ.)$
- Low Leakage Current
- $I_{DSS} = 300\mu A \text{ (Max.) (V}_{DS} = 0\text{V)}$
- Enhancement-Mode
  - $-V_{th} = 1.5 \sim 3.5V (V_{DS} = 10V, I_D = 1mA)$

#### Absolute Maximum Ratings (Ta = 25C)

CHARACTERISTIC		SYMBOL	RATING	UNIT	
Drain-Source Voltage		V <sub>DSS</sub>	800	٧	
Drain-Gate Voltage (Rs = 20kΩ)		V <sub>DGR</sub>	800	٧	
Gate-Source Voltage		Vsss	±30	٧	
Drain Current	DC	Ь	9	A	
	Pulse	I <sub>DP</sub>	27		
Drain Power Dissipation (Tc = 25°C)		Po	150	W	
Channel Temperature		T <sub>th</sub>	150	°C	
Storage Temperature Range			-55 ~ 150	°C	

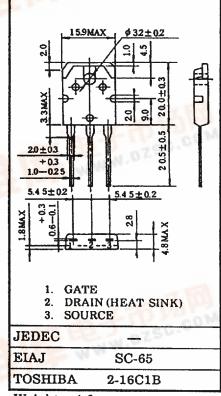
#### Thermal Characteristics

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Case	Ri(ch-c)	0.833	°C/W
Thermal Resistance, Channel to Ambient	ff(ch-a)	50	°C/W

This transister is an electrostatic sensitive device. Please handle with caution.

### Industrial Applications

Unit in mm



Weight: 4.6g



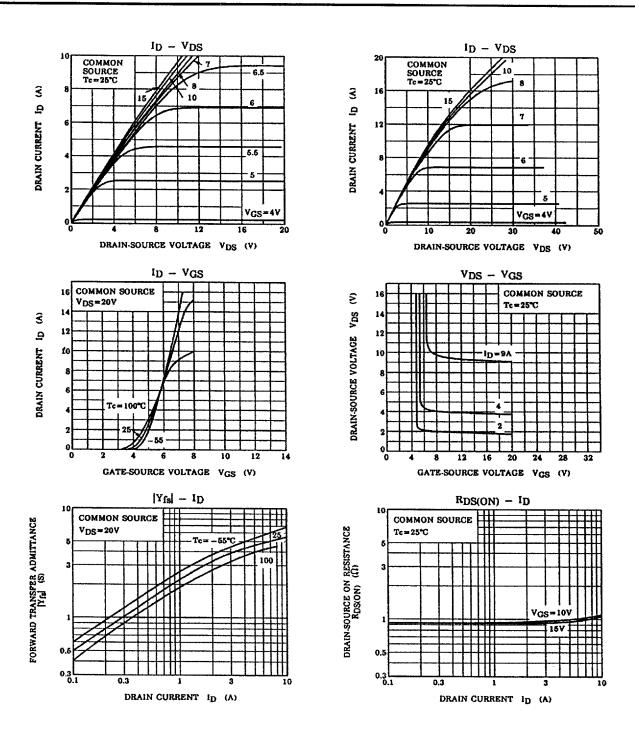
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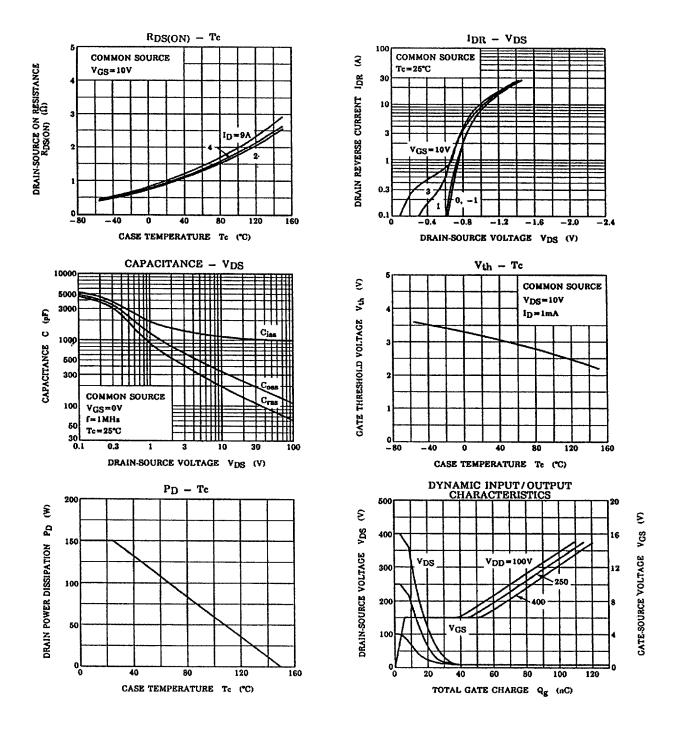
### Electrical Characteristics (Ta = 25C)

CHARAC	TERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage Current		ess	V <sub>GS</sub> = ±30V, V <sub>DS</sub> = 0V		-	±100	nΑ
Drain Cut-off Current		I <sub>DSS</sub>	V <sub>DS</sub> = 800V, V <sub>GS</sub> = 0V	-	_	100	μA
Drain-Source Breakdown Voltage		YOR) DSS	I <sub>D</sub> = 10mA, V <sub>GS</sub> = 0V	800	-		٧
Gate Threshold Voltage		<b>Y</b> h	V <sub>DS</sub> = 10V, I <sub>D</sub> = 1mA	1.5	_	3.5	٧
Drain-Source ON Resistance		Pos (ON)	V <sub>GS</sub> = 10V, I <sub>D</sub> = 4A	-	1.0	1.2	Ω
Forward Transfer	Transfer Admittance $ Y_{fs} $ $ V_{DS}  = 15V$ , $ b  = 4A$		V <sub>DS</sub> = 15V, I <sub>D</sub> = 4A	2.0	40	-	S
Input Capacitance		C <sub>iss</sub>	$V_{DS} = 25V, V_{GS} = 0V,$ $f = 1MHz$	-	1150	-	pF
Reverse Transfer Capacitance Output Capacitance		Çss		-	135	-	
		Coss		-	210	- 1	
Switching Time	Rise Time	tr		-	35	-	
	Turn-on Time	Бn	ID=4A	-	55	_	пѕ
	Fall Time	1	VGS OV I I VOUT	-	25	-	
	Turn-off Time	pu	$\begin{array}{c c} & R_{L} = \\ \hline & 100\Omega \\ \hline & V_{DD} = 400V \\ \hline & V_{IN} : t_{r}, t_{f} < 5ns, \\ \hline & Duty \le 1\%, t_{w} = 10\mu s \end{array}$	-	100	_	
Total Gate Charge (Gate-Source Plus Gate-Drain) Gate-Source Charge Gate-Drain ("Miller") Charge		Q <sub>g</sub>	V <sub>DD</sub> = 400V, V <sub>GS</sub> = -10V,	-	85	-	
		Q <sub>ps</sub>	I <sub>D</sub> = 9A	-	40	_	nC
		<b>G</b> d		-	45	-	

### Source-Drain Diode Ratings and Characteristics (Ta = 25C)

CHARACTERISTICS	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	dr	-	-	-	9	A
Pulse Drain Reverse Current	<b>D</b> RP	_	-	-	27	Α
Diode Forward Voltage	Vose	I <sub>DR</sub> = 9A, V <sub>GS</sub> = 0V			-2.0	٧
Reverse Recovery Time	<b>#</b>	I <sub>DR</sub> = 9A, V <sub>GS</sub> = 0V		300		ns
Reverse Recovered Charge	Q.	dl <sub>DR</sub> / <sub>dl</sub> = 100A/µs	_	26		μC





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